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(54) **ALIGNMENT PATTERN HAVING AN E
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(71) Applicant: **Micron Technology, Inc.**, Boise, ID
(US)

(72) Inventor: **Chinaru Takahashi**, Higashihiroshima
(JP)

(73) Assignee: **Micron Technology, Inc.**, Boise, ID
(US)

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(57) **ABSTRACT**

An apparatus includes an alignment pattern which comprises: a first line portion of a first material extending in a first direction; a second line portion of the first material extending in the first direction in parallel to the first line portion; a third line portion of the first material extending in a second direction perpendicular to the first direction such that the third line portion connects an edge of the first line portion and an edge of the second line portion; and a fourth line portion of a second material arranged between the first line portion and the second line portion and extending in the first direction.

